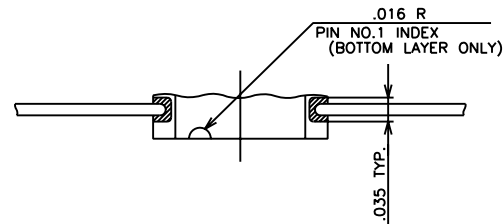
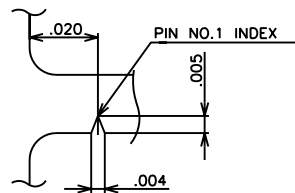
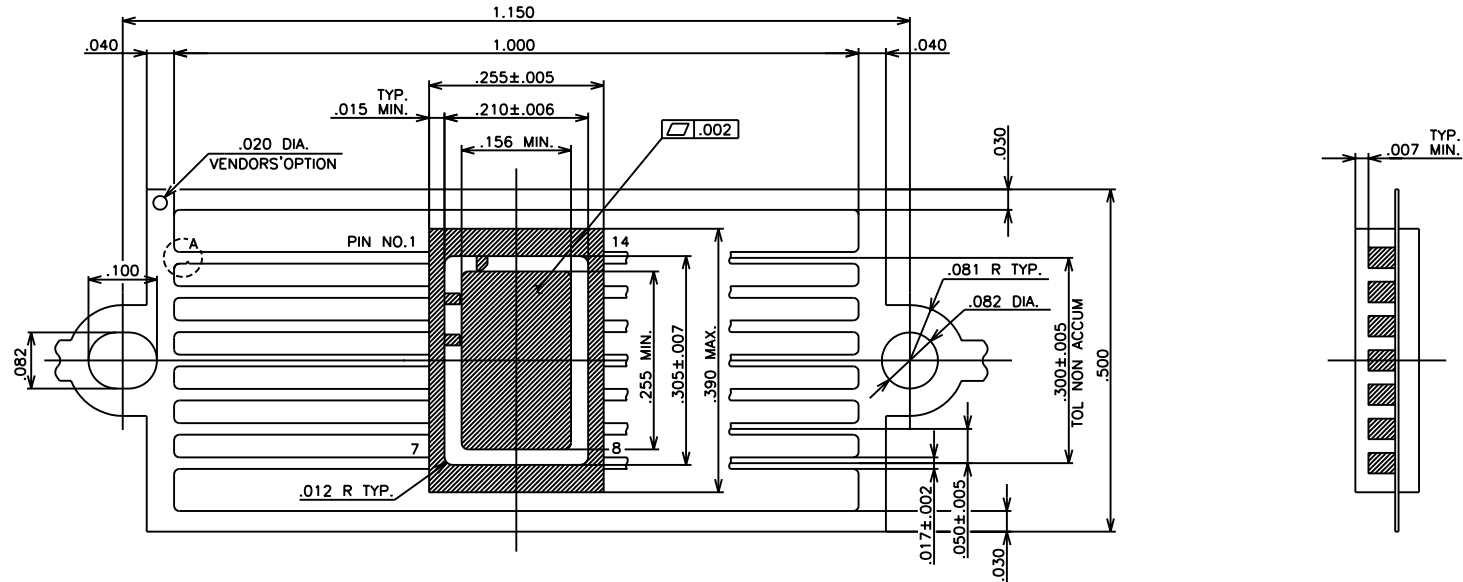


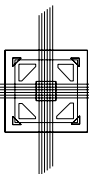
SSM P/N CCF01425



- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.

DETAIL A

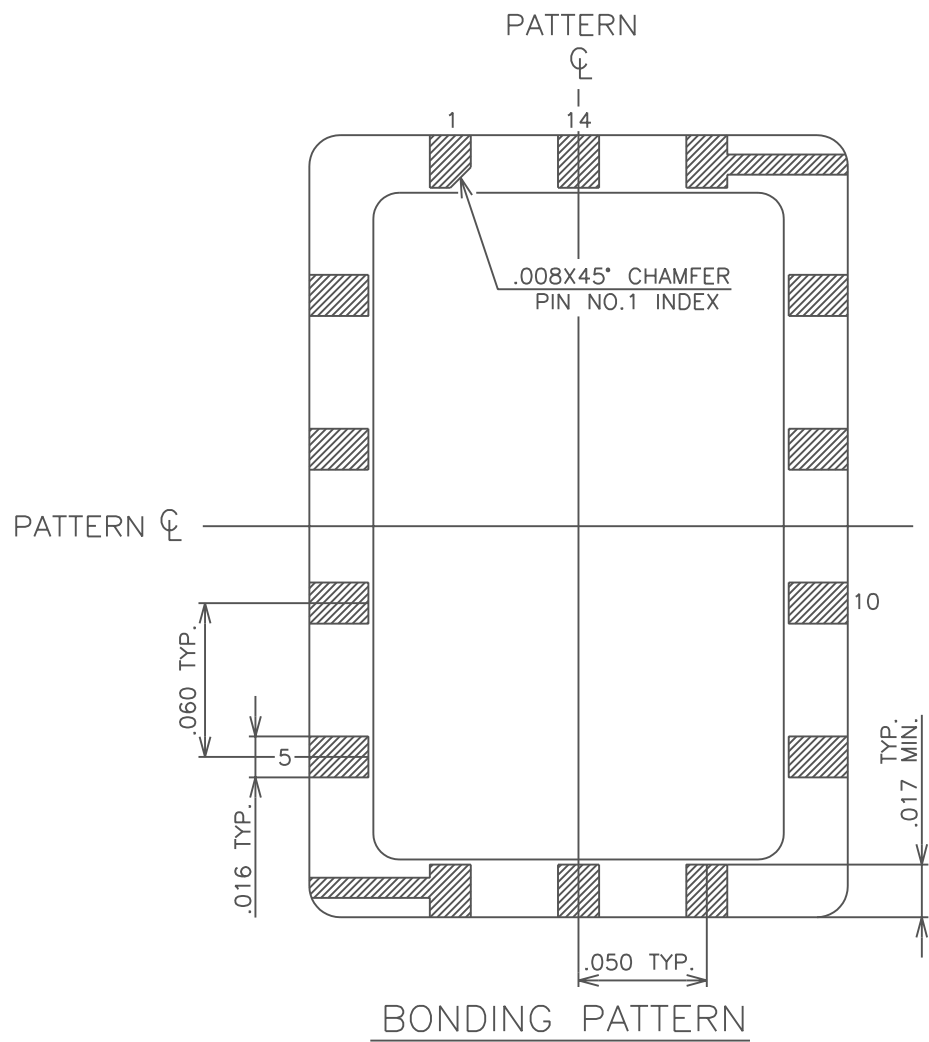
MODIFICATION REDRAWN : CONVERTED CAD DATA. ADDED : SHEET 2/2 CHANGED						NAME	TOLERANCE UNLESS OTHERWISE SPECIFIED		DRAWN		CHECKED		APPROVED		DATE	
						SCALE 8/1	MATERIAL AS INDICATED		S.T		T.A		M.F		DEC.28.89	
JUL.31.00 H.K H.TA/S.NI H.SA DATE DRAWN CHECKED APPROVED						KYOCERA CORPORATION KYOTO JAPAN		DRAWING NO. KD-F89980-D		SHEET 1/2						



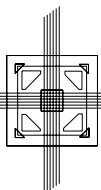
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MODIFICATION						NAME 14 LEAD FLAT PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN H.K	CHECKED H.TA/S.NI	APPROVED H.SA	DATE JUL.31.'00
						SCALE 20/1	MATERIAL				
	ADDED : THIS SHEET	JUL.31.'00	H.K	H.TA/S.NI	H.SA		THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-F89980-D		SHEET 2/2	



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